SPECIFICATION FOR APPROVAL

DESCRIPTION: Pitch 1.2 mm Wire	Го Board Connector, V/T ,SMT Type	
CUSTOMER PROD.NO/DWG.NO:		
E&T PROD.NO:	4280K-FXXN-XXX	
APPROBAL SHEET NO:		
E&T DWG. NO./DOCUMENT:	4280K-FXXN-XXX	
		REV: A9

PLEASE RETURN TO US ONE COPY OF SPECIFICATION FOR APPROVAL WITH YOUR APPROVED SIGNATURES.

APPROVED SIGNATURES						



ENTERY INDUSTRIAL CO., LTD.
E&T ELECTRONICS (DONG GUAN) CO., LTD.
E&T ELECTRONICS (SU ZHOU) CO., LTD.
E&T ELECTRONICS (NANKEEN)CO.,LTD.

Title :Pitch 1.2 mm Wire To Board Connector, V/T,SMT Type

Juno Chen Title: Pitch 1.2mm Wire To Board Connector, V/T,SMT Type						
A9	2014/11/18	This Document Contains Information That Is Proprietary To				
Rev	Description	E&T And Should Not Be Used Without Written Permission				
Document No.		Prepared By: Simon Wen	Date: 08,05'2010			
4280K-FXXN-XXX		Checked By:	Date: 1 8 7010			
420	OUX-1 AAIN-AAA	Approved By:	Date:			

GROUP AND TEST SEQUENCE

	Test of Examination				,	Test	t Gr	oup)			
	rest of Examination		В	C	D	Е	F	G	Н	I	J	K
1	Examination of Product	1,9	1,6	1,5	1,5	1,5	1,3	1,3	1,3	1,5	1,5	
2	Contact Resistance	2,6	2,5	2,4	2,4	2,4				2,4	2,4	
3	Insulation Resistance	3,7										
4	Dielectric Strength	4,8										
5	Insertion Force And Withdrawal Force		3									
6	Terminal / Housing Retention Force											1
7	Durability		4									
8	Vibration			3								
9	Heat Resistance				3							
10	Cold Resistance					3						
11	Humidity	5										
12	Solder Ability						2					
13	Resistance To Soldering Heat							2				
14	Steam Aging								2			
15	Salt Spray									3		
16	Temperature Cycling										3	

PRODUCT SPECIFICATION

1. SCOPE:

This specification covers the 1.00 mm pitch Wire To Board connector series.

2. PRODUCT NAME AND PART NUMBER:

Product Name	E&T Part Number
1.2mm Wire To Board Connector, V/T,SMT Type	4280K-FXXN-XXX

3. RATINGS:

Item	Standard	
Rated Voltage (MAX.)	50 V	AC/DC
Rated Current (M.)	1.5 A	
Ambient Temperature Range	-25 ⁰ C ∼	- +85°C

^{*}Including temperature rise in applying electrical current

4.PERFORMANCE:

4-1 Electrical Performance

	Item	Test Condition	Requirement
4-1-1	Contact Resistance	Test Current: 10 mA Max. Test Voltage: 20mV Max Test Method:EIA-364-06B	20 mΩ MAX.
4-1-2	Insulation Resistance	Test Voltage: 500V DC. Test Duration: 1 minutes. Test Method: EIA-364-21C	100 MΩ Min.
4-1-3	Test Voltage: 500 V AC. Test Time: 60 sec.		No Breakdown

4-2 Mechanical Performance

	Item	Test Condition	Requirement
4-2-1	Insertion Force And Withdrawal Force	Test Speed: 25±3 mm/min. Test Method: EIA-364-13B	See 5-1
4-2-2	Test Speed: 25mm/min. Terminal / Housing Retention Force		0.10kgf (Min)
4-2-3	Fitting Nail/ Housing Retention Force Apply axial pull out force at the speed rate of 25±3 mm/minute on the fitting nail assembled in the housing. EIA-364-29C		0.15kgf (Min)
		The contacts of connector shall be subject to 30 cycles of mating and unmating.	Contact Resistance
4-2-4	Durability	Test Method: EIA-364-09C	\leq 20 m Ω

4-3 Environmental Performance and Others

I	ltem	Test Condition	Require	ment
		Amplitude : 1.5 mm Frequency range: 10~55~10 Hz in 1 minute	Appearance	No Damage
4-3-1	Vibration	Duration: 2 hours in each X.Y.Z axes Current: 100mA. Test Method: EIA-364-28D	Contact Resistance	≤20 mΩ
		Test Method. Elik 664 265	Discontinuity	1µsec
4-3-2	Heat	Temperature: 85±3°C Duration: 96 hours	Appearance	No Damage
7 0 2	Resistance		Contact Resistance	\leq 20 m Ω
4-3-3	Cold	Temperature: -40±2°C Duration: 96 hours	Appearance	No Damage
4-3-3	Resistance		Contact Resistance	\leq 20 m Ω
		Temperature: $40\pm2^{\circ}$ C Relative Humidity: $90\sim95\%$	Appearance	No Damage
4-3-4	Humidity	Duration: 96 hours Test Method: EIA-364-31B	Contact Resistance	\leq 20 m Ω
-3-4	riamilalty		Insulation Resistance	≥100 M Ω
			Dielectric Strength	Must meet 4-1-3
4-3-5	Solder Ability	Soldering Time : 3 ± 0.5 sec Solder Temperature : $245\pm5^{\circ}$ C Test Method: EIA-364-52	Solder Wetting	95% Of Immersed Area Must Show No Voids, Pin Holes

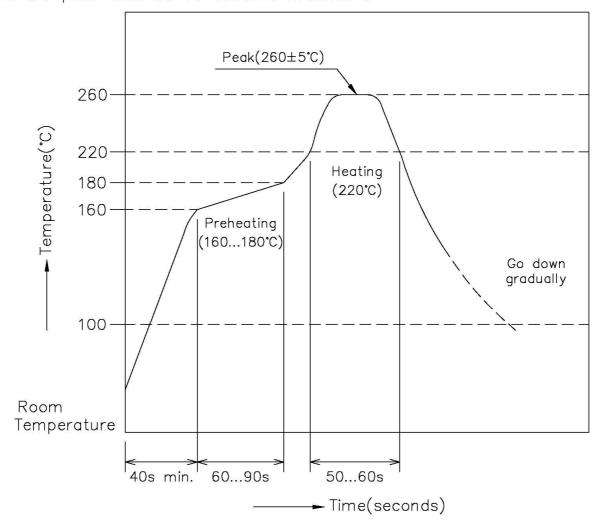
	Item	Test Condition	Requi	rement
4-3-6	Resistance To Soldering Heat	Soldering Time : 10±0.5 sec Solder Temperature : 260±5°C Test Method: EIA-364-56C	Appearance	No Damage
		Steam Aging Temperature : 98±2℃ Duration: 8 hours Solder Temperature : 245±5℃	Appearance	No Damage
4-3-7	Steam Aging	Soldering Time : 3±0.5 sec Test Method: EIA-364-17B	Solder Wetting	95% Of Immersed Area Must Show No Voids, Pin Holes
4-3-8	Salt Spray	Chamber Temperature : 35±2°C Air Tank Temperature : 47±1°C Salt Solution : 5 ± 0.5% Duration : 48 hours	Appearance	No Damage
700	Guit Opray	Test Method: EIA-364-26B	Contact Resistance	\leq 20 m Ω
4-3-9	Temperature	5 cycles of : a) - 40 ±3°C 30 minutes b) +25 ±3°C 30 minutes	Appearance	No Damage
4-3-9	Cycling	c)+ 85 ±2 $^{\circ}$ C 30 minutes Test Method: EIA-364-31B	Contact Resistance	\leq 20 m Ω

5-1: Mating & Unmating Force Requirement(Unit: Kg)

Pin No.	Insertion Force (MAX)	Withdrawal Force (Min)
2	2.00	0.10
3	2.10	0.15
4	2.20	0.20
5~10	2.30	0.25

INFRARED REFLOW CONDITION

- 1) Ascending time to preheating temperature 170°C shall be 40 seconds minimum
- 2) Preheating shall be fixed at 160...180°C for 60...90 seconds.
- 3) Heating shall be fixed at 220°C for 50...60 seconds.
- 4) At 260±5°C peak shall be 10 seconds maximum.



Wire-to-Board Connectors Handling Precautions

This manual is to describe basic precautions. When there are doubtful points in use of, please contact E&T.

1. Common Handling Precautions

- Do not expose E&T's Wire-to-Board connector, processing process product and processing product to corrosive substance, corrosive gas, high temperature and high humidity and direct sunshine. It causes corrosion of contact and deterioration of insulation performance of housing, etc., so that it causes motion defect of appliances.
- Do not apply external load to E&T's Wire-to-Board connector, processing process product and processing product. Deformation and breakage, etc. occur, and it causes performance defect of.
- There may be slight differences in the housing coloring, but there will be no influence on the product's performance.
- Please do not conduct any "washing process" on the connector because it may damage the product's function.

2. PC Board Precautions

- Exercise caution when handling boards with the connectors installed. Do not apply any forces affecting soldered joints. (see figure 1).
- The mounting specification for coplanarity does not include the influence of warpage of the printed circuit board. (see figure 1).

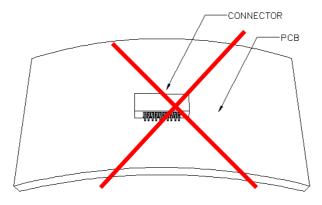
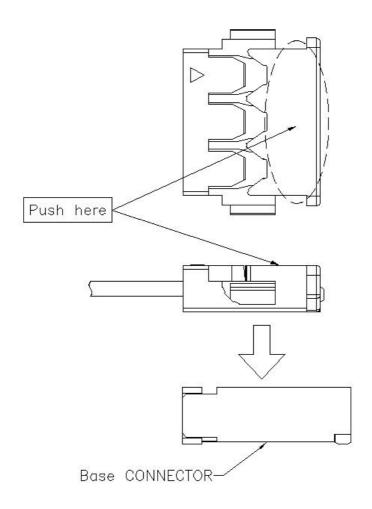
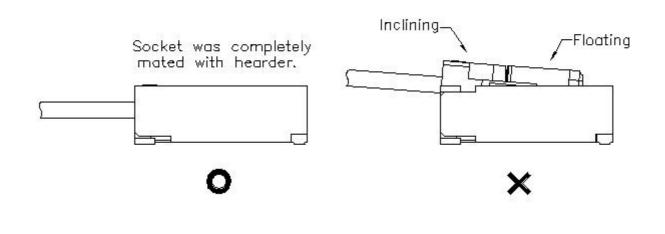


Figure 1.

3. Operation

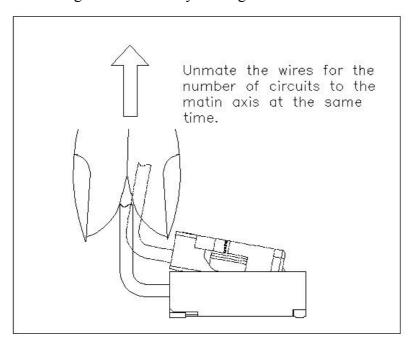
- Mating Method of Connector
 - 1. Mate a socket connector on the mating axis to a base connector.
 - 2. Confirm that the socket housing is pushed and it mates securely.

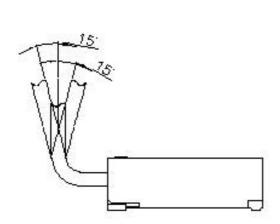


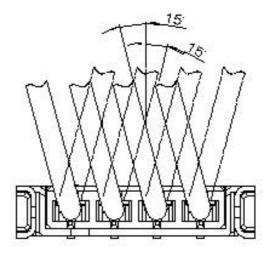


• Un mating Method of Connector

Un mating the connector by holding wires in a bundle within 15 degrees to the mating axis.

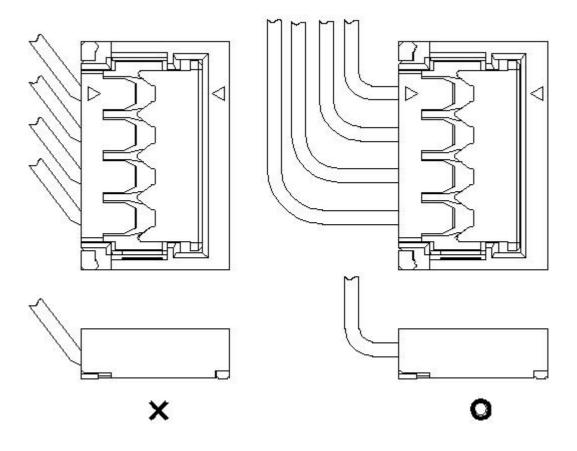






make allowance so that power of more than the tension by the bending wire is not applied to the connector when you handle the wire.

(Provide space above the connector in order to form wire by bending and do not apply tension to the connector as below.)



RELEASE HISTORY

Rev.	Revisions	Date	Executor	Description
A0	RB100410	2010/08/05	Simon	First Release
A1	RB100410	2010/10/15	Simon	4-3-4 \geq 1000MΩ Modify \geq 100MΩ
A2	RB100410	2010/12/07	Simon	R/A,SMT Type Modify V/T,SMT Type
A3	RB101202	2010/12/15	Simon	4-2-2 0.30kgf (Min) Modify 0.25kgf (Min)
A4	RB101202	2011/01/12	Simon	4280K-FXXN-XXR Modify 4280K-FXXN-XXX
A5	RB101202	2011/03/08	Simon	4-2-2 0.25kgf (Min) Modify 0.15kgf (Min)
A6	RB101202	2011/05/10	Simon	4-2-3 Modify Fitting Nail/ Housing Retention Force
A7	RB101202	2011/05/25	Simon	4-2-2 0.15kgf (Min) Modify 0.10kgf (Min)
A8	REN111012	2011/10/14	Juno	Add Handling Precautions
A9	REN141107	2014/11/18	Juno	Modify CR